

TK PASTE CR-5930

◆ Product benefits

- A thermosetting, one-component epoxy conductive adhesive, containing our unique shape silver particles.
- Can be cured at 80°C, making it ideal for conductive bonding applications for heat-sensitive components.
- Have high adhesive strength, and its conductivity does not deteriorate even after drop impact test.
- Non-solvent based and suitable for conductive bonding applications for optical components.
- Have long pot-life and good applicability with dispensers.

◆ Typical properties

	Typical value	Remarks
Base resin	One-component epoxy	Non-solvent type
Silver content (wt.%)	55-65	Unique shape silver particles.
Appearance	Gray paste	
Viscosity (Pa·s)	15~30	E type viscosity meter: 5rpm at 25°C
Specific gravity (-)	2.6	At 25°C
How to use	Air puls dispenser	Internal diameter of needle: >0.25mm
Storage condition	-10°C or below	Shelf life: 6months after manufacture
Pot life (hr)	48	@25°C
Typical curing schedule	80°C×1hr	Alternate curing schedule: 120°C×10min
Specific resistance (Ω·cm)	2×10^{-2}	4-terminal method
Glass transition temperature (T _g) (°C)	75	DMA method
Storage modulus (GPa)	4.8	DMA method at 25°C
Coefficient of thermal expansion (ppm/°C)	55	α1
	185	α2

Data in this document is based on evaluation results and does NOT guarantee product characteristics at use.
Make sure to try the product with equipment and adherend to be used.